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Mechanical standardization of semiconductor devices –

Part 6-1:
General rules for the preparation of outline drawings of surface mounted semiconductor device packages –
Design guide for gull-wing lead terminals

Normalisation mécanique des dispositifs à semi-conducteurs –

Partie 6-1:
Règles générales pour la préparation des dessins d'encombrement des dispositifs à semiconducteurs pour montage en surface –
Guide de conception pour les boîtiers à broches en forme d'ailes de mouette

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International Electrotechnical Commission 3, rue de Varembé Geneva, Switzerland
Telefax: +41 22 919 0300 e-mail: inmail@iec.ch IEC web site http://www.iec.ch

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-1: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Design guide for gull-wing lead terminals

FOREWORD

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International Standard IEC 60191-6-1 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/459/FDIS	47D/470/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2003. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-1: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Design guide for gull-wing lead terminals

1 Scope

This part of IEC 60191 covers the requirements for the design rule of terminal shape plastic packages with gull-wing leads; e.g., QFP, SOP, SSOP, TSOP, etc. which are packages classified as Form E in IEC 60191-4 [1)]. This publication is intended to establish common rules on terminal shapes irrespective of package types.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-6:1990, *Mechanical standardization of semiconductor devices – Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages*

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1) IEC 60191-4:1999, *Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor device packages*